

Product Documentation

CC6A-T1D

**AT-Cut
Quartz Crystal Unit
16 MHz – 70 MHz**

2. Product Description

The CC6A-T1D is a high frequency SMT Quartz Crystal Unit that incorporates an AT-Cut Quartz Crystal Resonator. The Quartz Crystal Resonator operates under vacuum condition in a hermetically sealed ceramic package with ceramic lid.

Suitable oscillator-circuitries can operate the CC6A-T1D Quartz Crystal Units in fundamental mode in the frequency range of 16 MHz – 70 MHz. For technical assistance for optimizing oscillator-circuitries please contact Micro Crystal under sales@microcrystal.com

2.1. Application Examples

Telemetry
Optical Network
Airborne Equipment
Radio Communications
Health Care and Medical

2.2. Ordering Information

Example: CC6A-T1D 24.000 MHz CL: 20.0 pF -50/+50ppm TA QI

Code	Operating temperature range
TA (Standard)	-40 to +85°C
TB	-40 to +125°C
TC	-55 to +125°C

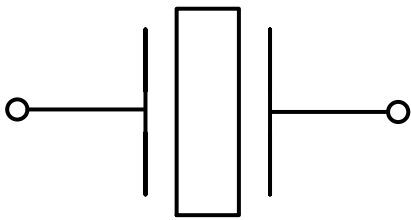
Code	Qualification
QI (Standard)	Industrial Grade
QS	Custom Specification

3. Electrical Characteristics

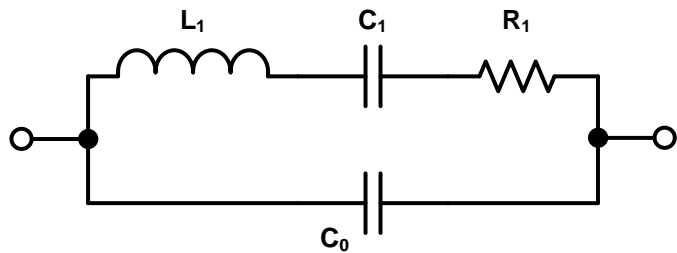
3.1. Equivalent Electrical Model

The Quartz Crystal Unit is a passive component with no polarity. The equivalent circuit of the quartz crystal at its fundamental resonance frequency is represented by the Equivalent Electrical Model:

Electrical Symbol:



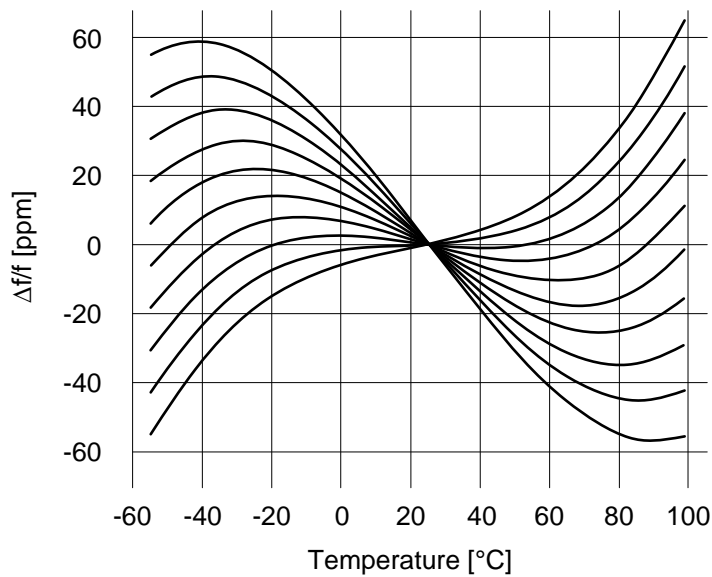
Equivalent Electrical Model:



- L_1 Motional Inductance
- C_1 Motional Capacitance
- R_1 Motional Resistance (ESR)

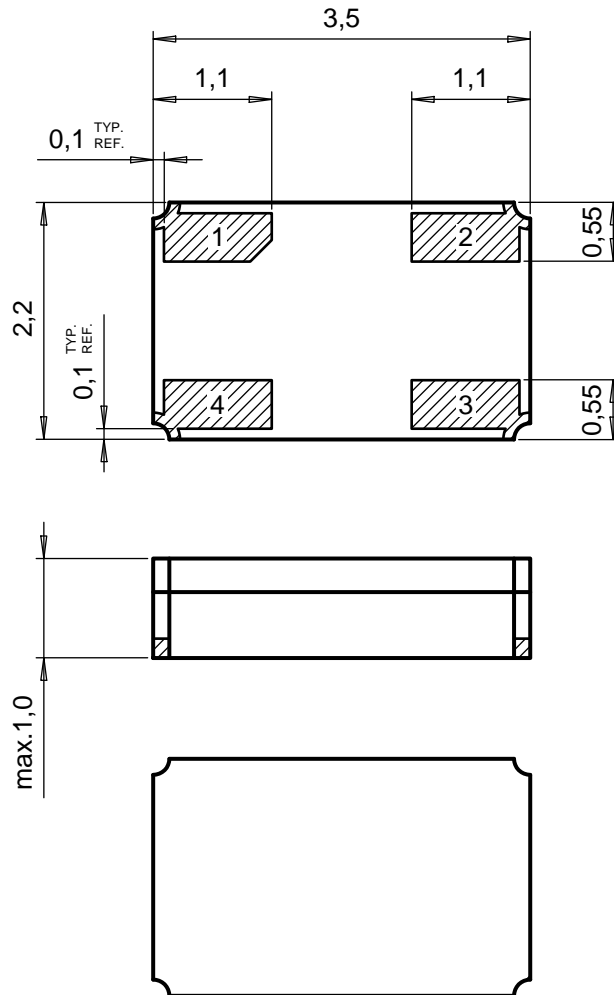
- C_0 Static Capacitance (Shunt capacitance)

3.2. Frequency vs Temperature Characteristics



4. Mechanical Properties

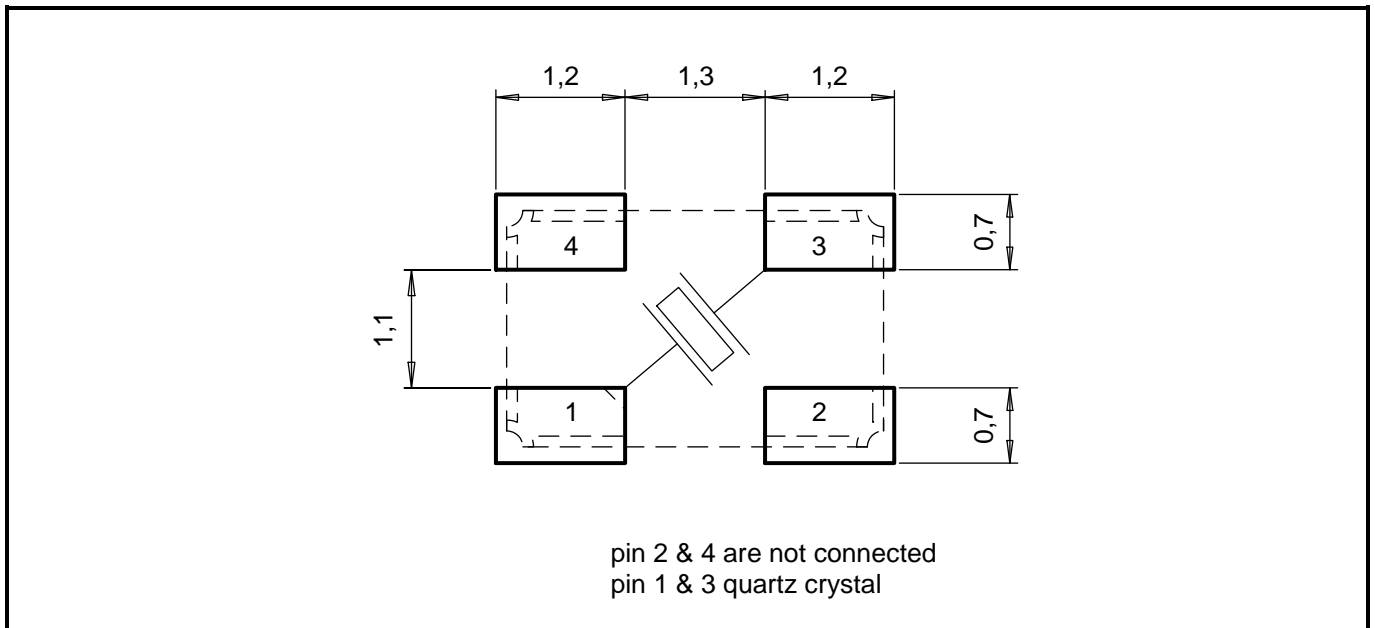
4.1. Package Dimension



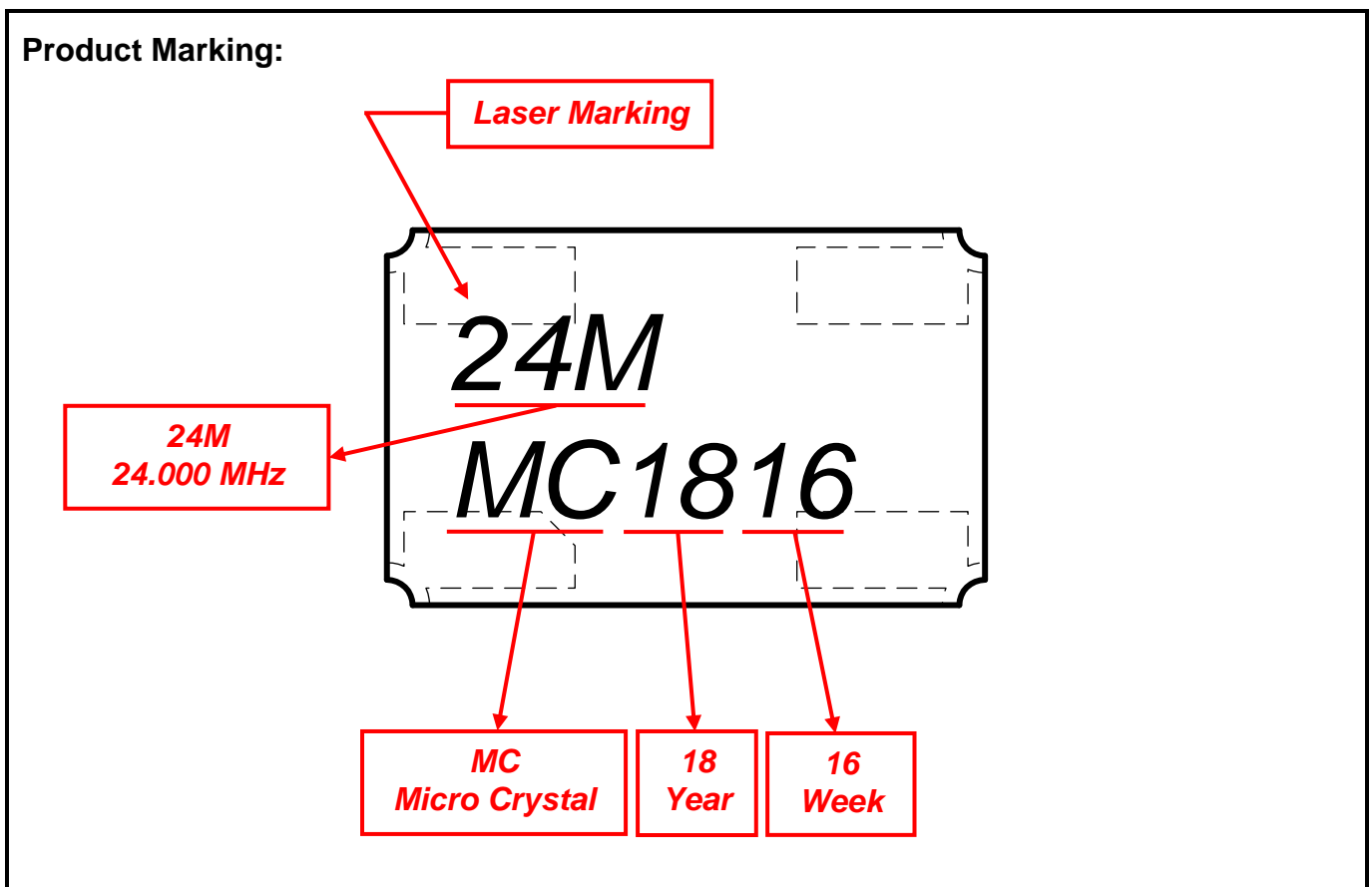
pin 2 & 4 are not connected
pin 1 & 3 quartz crystal

Tolerances: unless otherwise specified ± 0.1 mm
Drawing: CC6A-T1D_Pack-drw_20180418

4.2. Recommended Solderpad Layout



4.3. Product Marking



5. Material Composition Declaration & Environmental Information

5.1. Homogenous Material Composition Declaration

Homogenous material information according to IPC-1752 standard

Material Composition CC6A-T1D:

No.	Item Component Name	Sub Item Material Name	Material Weight		Substance Element	CAS Number	Comment
			(mg)	(%)			
1	Resonator	Quartz Crystal	0.70	100%	SiO ₂	14808-60-7	
2	Electrodes	Cr+Au	0.01	6%	Cr	7440-47-3	
				94%	Au	7440-57-5	
3	Housing	Ceramic	20.85	100%	Al ₂ O ₃	1344-28-1	
4	Seal	Solder Preform	1.70	80%	Au80 / Sn20	Au: 7440-57-5	
				20%		Sn: 7440-31-5	
5	Terminations	Internal and external terminals	0.95	80%	W	W: 7440-33-7	Tungsten
				15%	Ni	Ni: 7440-02-0	Nickel plating
				5%	Au 0.5 micron	Au: 7440-57-5	Gold plating
6	Conductive adhesive	Silver filled glue	0.29	88%	Ag	Ag: 7440-22-4	
				12%	Glue		
		Unit weight typ. ±10%	24.5				

5.2. Material Analysis & Test Results

Homogenous material information according to IPC-1752 standard

No.	Item Component Name	Sub Item Material Name	RoHS						Halogen				Phthalates			
			Pb	Cd	Hg	Cr+6	PBB	PBDE	F	Cl	Br	I	BBP	DBP	DEHP	DINP
1	Resonator	Quartz Crystal	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
2	Electrodes	Cr+Au	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
3	Housing	Ceramic	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
4	Seal	Solder Preform	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
5	Terminations	Int. & ext. terminals	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
6	Conductive adhesive	Silver filled glue	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
	MDL	Measurement Detection Limit	2 ppm			5 ppm		50 ppm				0.003%		0.01%		

nd = not detectable

Test methods:

RoHS	Test method with reference to IEC 62321-5: 2013	MDL: 2 ppm (PBB / PBDE: 5 ppm)
Halogen	Test method with reference to BS EN 14582:2007	MDL: 50 ppm
Phthalates	Test method with reference to EN 14372	MDL: 0.003 % (DINP 0.01%)

5.3. Recycling Material Information

Recycling material information according to IPC-1752 standard.

Element weight is accumulated and referenced to the unit weight of 24.5 mg.

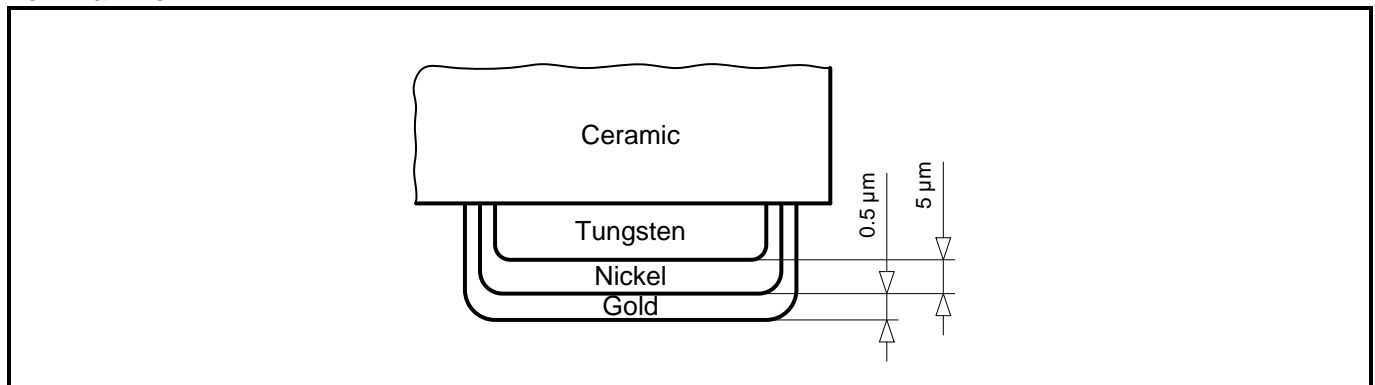
Item Material Name	No.	Item Component Name	Material Weight		Substance Element	CAS Number	Comment
			(mg)	(%)			
Quartz Crystal	1	Resonator	0.70	2.86	SiO ₂	14808-60-7	
Chromium	2	Electrodes	0.0006	0.002	Cr	7440-47-3	
Ceramic	3	Housing	20.85	85.10	Al ₂ O ₃	1344-28-1	
Gold	2 4 5	Electrodes Seal Terminations	1.42	5.78	Au	7440-57-5	
Tin	4	Seal	0.34	1.39	Sn	Sn: 7440-31-5	
Nickel	5	Terminations	0.14	0.58	Ni	Ni: 7440-02-0	
Tungsten	5	Terminations	0.76	3.10	W	W: 7440-33-7	
Silver	6a	Conductive adhesive	0.26	1.04	Ag	Ag: 7440-22-4	
Glue	6b	Conductive adhesive	0.035	0.14	Glue		
Unit weight (total) typ. ±10%			24.5	100			

5.4. Environmental Properties & Absolute Maximum Ratings

Package	Description
Ceramic Package	Hermetic ceramic-package, no-leads

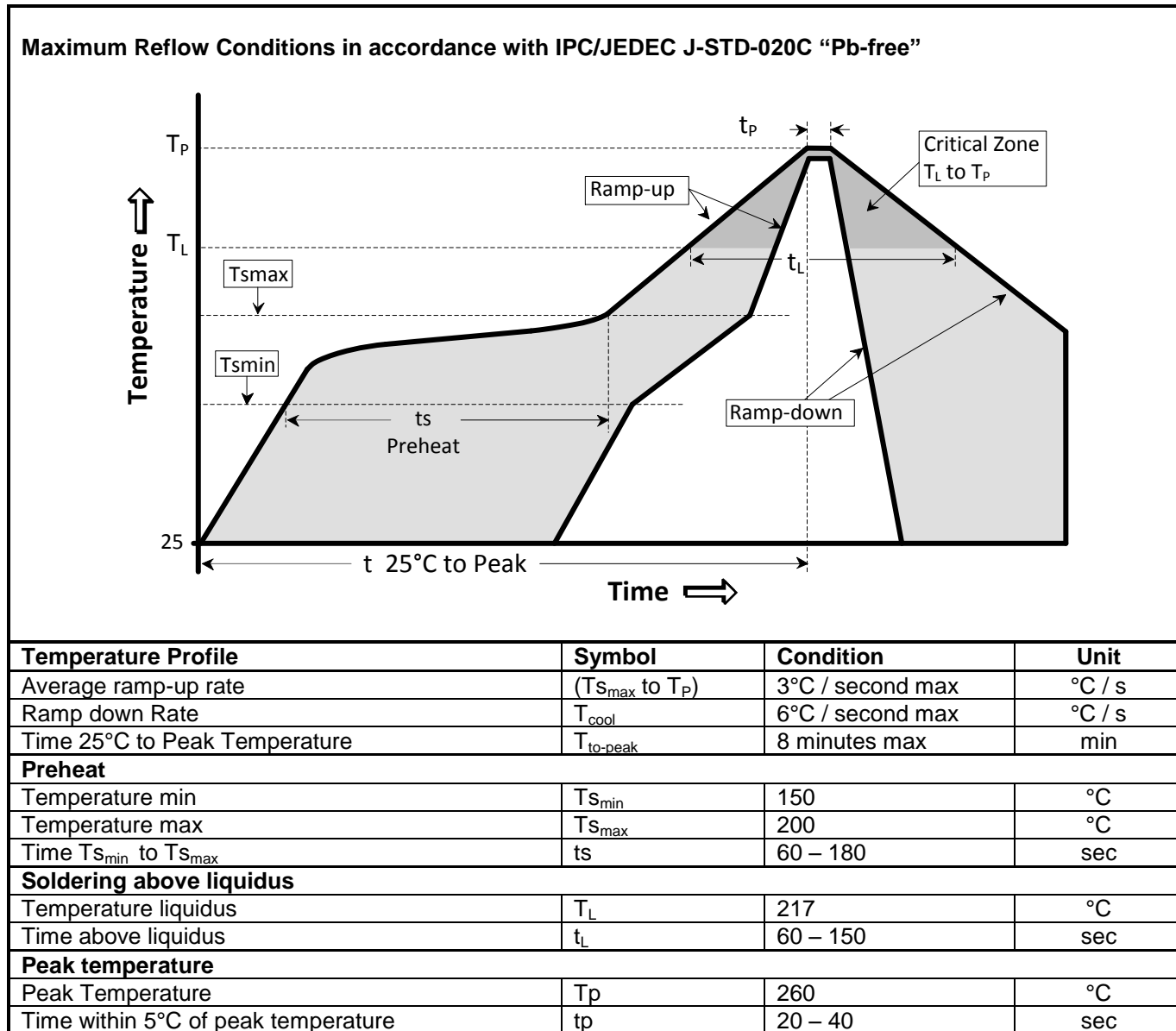
Parameter	Directive	Conditions	Value
Product weight (total)			24.5 mg
Storage temperature	MIL-O-55310	Store as bare product	-55 to +125°C
Moisture sensitivity level (MSL)	IPC/JEDEC J-STD-020D		MSL 1
FIT / MTBF			available on request

Terminal finish:



6. Application Information

6.1. Soldering Information



6.2. Handling Instructions for Quartz Crystal Units

The built-in AT-cut crystal consists of pure Silicon Dioxide in crystalline form. The cavity inside the package is evacuated and hermetically sealed in order for the crystal blank to function undisturbed from air molecules, humidity and other influences.

Shock and vibration:

Keep the crystal / module from being exposed to **excessive mechanical shock and vibration**. Micro Crystal guarantees that the crystal / module will bear a mechanical shock of 5000 g / 0.3 ms.

The following special situations may generate either shock or vibration:

Multiple PCB panels - Usually at the end of the pick & place process the single PCBs are cut out with a router. These machines sometimes generate vibrations on the PCB that have a fundamental or harmonic frequency close to the resonance frequency of the crystal unit. This might cause breakage of crystal blanks due to resonance. Router speed should be adjusted to avoid resonant vibration.

Ultrasonic cleaning - Avoid cleaning processes using ultrasonic energy. These processes can damage crystals due to mechanical resonance of the crystal blank.

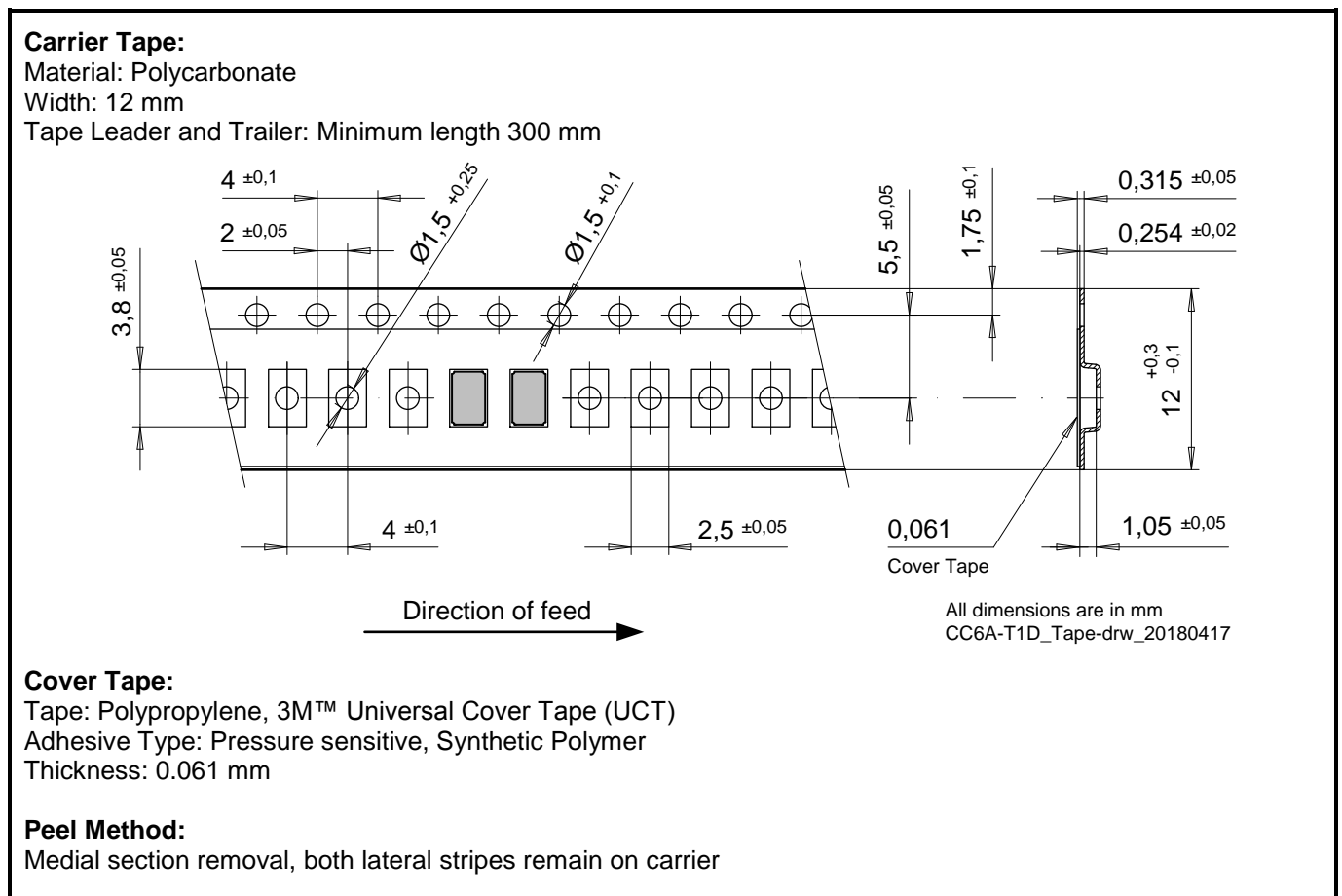
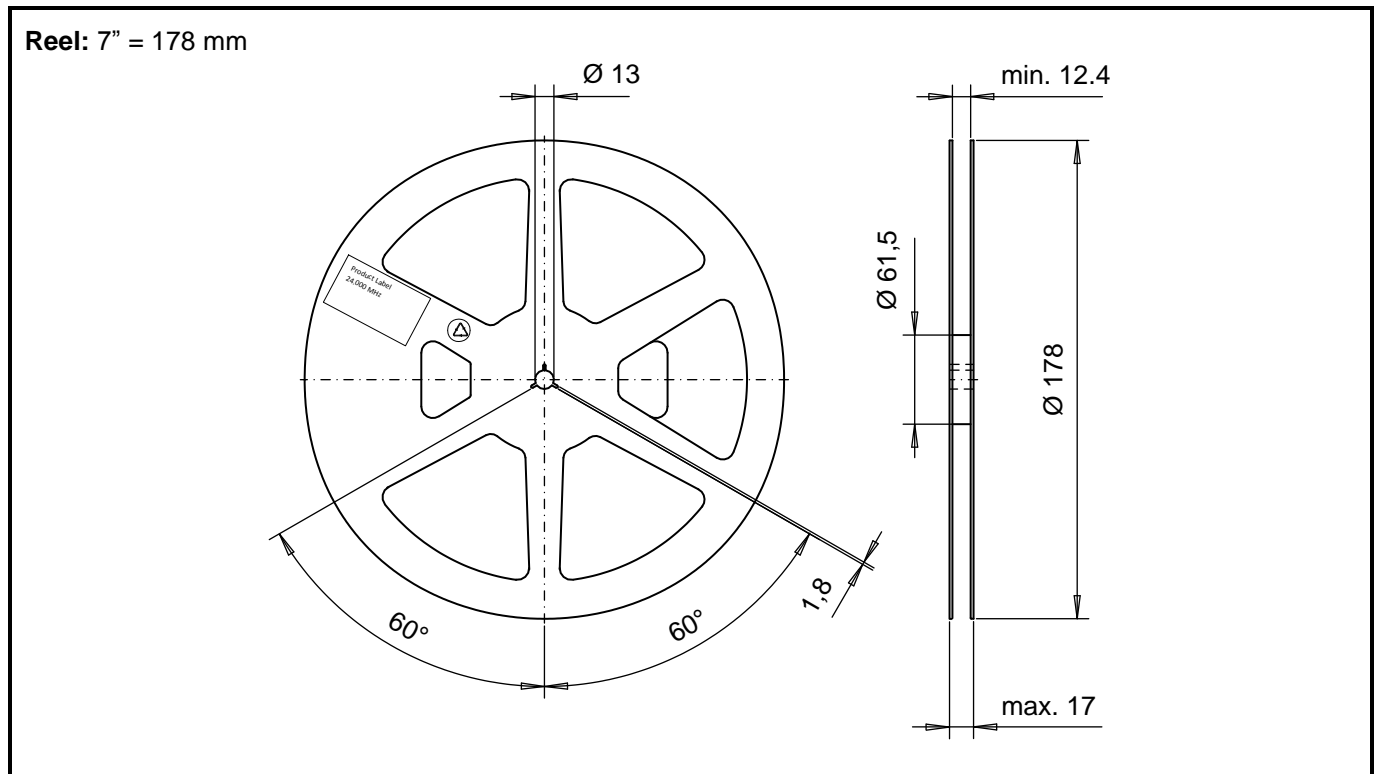
Overheating, rework high temperature exposure:

Avoid overheating the package. The package is sealed with a seal ring consisting of 80% Gold and 20% Tin. The eutectic melting temperature of this alloy is at 280°C. Heating the seal ring up to >280°C will cause melting of the metal seal which then, due to the vacuum, is sucked into the cavity forming an air duct. This happens when using hot-air-gun set at temperatures >300°C.

Use the following methods for rework:

- Use a hot-air- gun set at 270°C.
- Use 2 temperature controlled soldering irons, set at 270°C, with special-tips to contact all solder-joints from both sides of the package at the same time,

7. Packing & Shipping Information



8. Compliance Information

Micro Crystal confirms that the standard product Quartz Crystal Unit CC6A-T1D is compliant with “EU RoHS Directive” and “EU REACH Directives”.

Please find the actual Certificate of Conformance for Environmental Regulations on our website:

[CoC_Environment_CC&CM-Series.pdf](#)

9. Document Revision History

Date	Revision #	Revision Details
April 2018	1.0	First release

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A COMPANY OF THE  SWATCH GROUP

Micro Crystal AG
Muehlestrasse 14
CH-2540 Grenchen
Switzerland

Phone +41 32 655 82 82
Fax +41 32 655 82 83
sales@microcrystal.com
www.microcrystal.com